

MT29F64G08CECDBJ4-10

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Data Sheets (1)

Data Sheet

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Orderable Part Information

Status	Production	Alternative Part	N/A
FBGA Code	NW714	SPD Data	N/A
MBQual Data	N/A	Shipping Media	N/A
PLP	No	Start Date	N/A

Specs

Density	64Gb	Status	Production
RoHS	Yes	Width	x8
Voltage	3.3V	Package	VBGA
Pin Count	132-ball	MT/s	200 MT/s
I/O	Common	Product Name	

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08/2014	IBIS: NAND 32Gb MLC Async/Sync, L83A

FAQs

- » Do you support small block devices?
- » How much ECC do I need to support your devices?
- » I am using the correct amount of error correction code (ECC) for the NAND device, but I'm still seeing bitbyte errors in data I read back from the NAND device.
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Sim Models & Software

Title & Description	Secure	ID	Updated
HSpice: NAND 32Gb MLC Async/Sync, L83A Rev 2.1		L83A	08/2014
IBIS: NAND 32Gb MLC Async/Sync, L83A Rev 2.1		L83A	08/2014

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- + Do you support small block devices?
- + How much ECC do I need to support your devices?
- + I am using the correct amount of error correction code (ECC) for the NAND device, but I'm still seeing bitbyte errors in data I read back from the NAND device.

- + How do I achieve greater PROGRAM/READ throughput for the NAND device?
- + How is Nvb specified?
- + I am seeing a lot of READ DISTURB errors. Can you tell me if there is a problem with your part?
- + I've heard that NAND has too many errors to boot from. Is this true?
- + Should I be marking blocks bad due to READ errors?
- + When I issue a Read ID command (90h) to a two-die NAND device, I get a device ID back that states it is a one-die NAND device.
- + Where can I find additional technical information about Micron NAND devices that is not covered in the device data sheets?
- + Where can I find simulation models for NAND Flash devices?
- + Why am I getting a bitbyte error reading back the information I programmed into the NAND device?
- + Why doesn't the NAND Flash device respond correctly to commands issued to it?
- + What is a "bank"?
- + What is the impedance tolerance of the driver in match-impedance mode relative to the expected value base on the perfect reference resistor connected to ZQ pin?
- + Does thermal information change for IT parts?
- + My design was based on a specification stating the JTAG was relative to VDD (1.8V), but now we've discovered that JTAG is actually relative to VDDQ (1.8V). It's a fairly significant board spin to change this; what do I risk by leaving the design as-is? I assume that the specification is still for VDDQ + 0.3V = 1.8V, but with CMOS parts there's no way I can guarantee that it won't swing past that on transitions.
- + Should the ECC memory chip share chip select and CKE signals with the other two main memory chips in our point-to-point application?

- + Who do I contact if I have questions about my [bugmicron.com](#) order?